

# **CRMQGL1012A** N-Channel 100V, 10mΩ Typ. Power MOSFET

### Description



• 100V, 50A

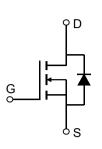
 $R_{DS(ON)}$ Typ = 10m $\Omega$  @ V<sub>GS</sub> = 10V

 $R_{DS(ON)}$ Typ = 13m $\Omega$  @ V<sub>GS</sub> = 4.5V

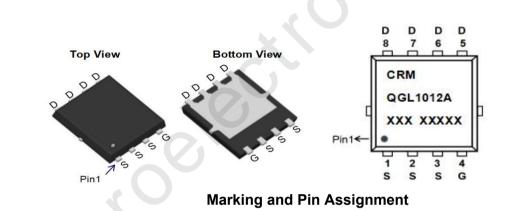
- Advanced Split Gate Trench Technology
- Excellent R<sub>DS(ON)</sub> and Low Gate Charge
- Lead Free
- 100% UIS TESTED!
- 100% ΔVds TESTED!

## **Application**

- Load Switch
- PWM Application
- Power Management



## Schematic Diagram



### Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMQGL1012A	CRMQGL1012A	PDFN3.3x3.3-8L	TAPING	13"	5000	50000

### Absolute Maximum Ratings (@ T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter		Value	Units
$V_{\text{DS}}$	Drain-to-Source Voltage		100	V
$V_{GS}$	Gate-to-Source Voltage		±20	V
	Continuous Drain Current	$T_c = 25^{\circ}C$	50	А
I <sub>D</sub>		T <sub>C</sub> = 100°C	30	А
I <sub>DM</sub>	Pulsed Drain Current <sup>(1)</sup>		200	А
E <sub>AS</sub>	Single Pulsed Avalanche Energy <sup>(2)</sup>		56	mJ
P <sub>D</sub>	Power Dissipation	T <sub>c</sub> = 25°C	56	W
$R_{ extsf{ heta}JC}$	Thermal Resistance, Junction to Case		2.2	°C/W
Τ <sub>J</sub> , Τ <sub>stg</sub>	Junction & Storage Temperature Range		-55 to 150	°C



### **Electrical Characteristics** (T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Off Chara	acteristics					
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V	100	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V	-	-	1.0	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
On Chara	acteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS}$ = $V_{GS}$ , $I_D$ = 250 $\mu$ A	1	1.7	2.5	V
_	(2)	V <sub>GS</sub> = 10V, I <sub>D</sub> = 30A	-	10	13	mΩ
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(3)</sup>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 25A	-	13	17	mΩ
Dynamic	Characteristics					
C <sub>iss</sub>	Input Capacitance		-	1500	-	pF
C <sub>oss</sub>	Output Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 25V, f = 1MHz	-	840	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			30	-	pF
Q <sub>g</sub>	Total Gate Charge		<u> </u>	35	-	nC
$Q_{gs}$	Gate Source Charge	$V_{GS} = 0$ to 10V $V_{DS} = 50V$ , $I_{D} = 15A$	-	4.5	-	nC
$Q_{gd}$	Gate Drain("Miller") Charge	$v_{\rm DS} = 50$ v, $I_{\rm D} = 15$ A	-	8	-	nC
Switchin	g Characteristics					
t <sub>d(on)</sub>	Turn-On DelayTime		-	16	-	ns
t <sub>r</sub>	Turn-On Rise Time	V <sub>GS</sub> = 10V, V <sub>DD</sub> =50V	-	13	-	ns
$t_{d(off)}$	Turn-Off DelayTime	$I_D$ = 15A, $R_{GEN}$ = 3 $\Omega$	-	37	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	17	-	ns
Drain-So	urce Diode Characteristics and M	lax Ratings				
I <sub>s</sub>	Maximum Continuous Drain to Source Di	ode Forward Current	-	-	50	А
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	200	А
$V_{SD}$	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 30A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time		-	38	-	ns
Qrr	Body Diode Reverse Recovery Charge	I <sub>F</sub> = 12A, di/dt = 100A/us	-	35	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. E<sub>AS</sub> condition: Starting T<sub>J</sub>=25C, V<sub>DD</sub>=50V, V<sub>G</sub>=10V, R<sub>G</sub>=250hm, L=0.5mH, I<sub>AS</sub>=15A

3. Pulse Test: Pulse Width  ${\leqslant}300\mu s,$  Duty Cycle  ${\leqslant}0.5\%.$ 



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## **Test Circuit**

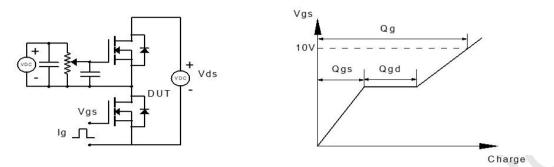
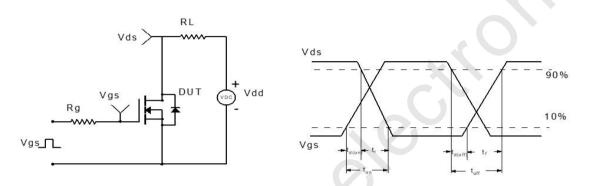
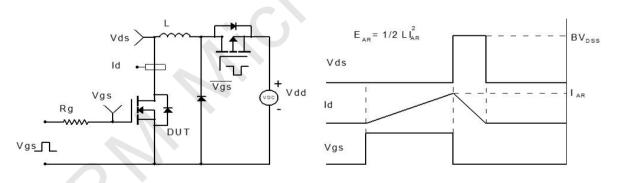


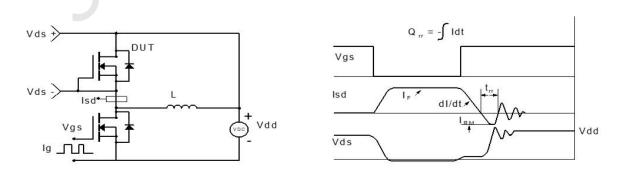
Figure 1: Gate Charge Test Circuit & Waveform



### Figure 2: Resistive Switching Test Circuit & Waveform



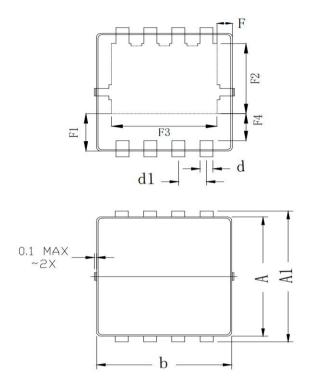
### Figure 3: Unclamped Inductive Switching Test Circuit& Waveform

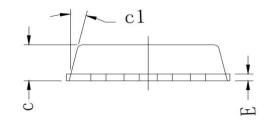






## Package Mechanical Data(PDFN3.3x3.3-8L)





	COMMON DIN	IENSION (MM)	
PKG	PDFN 3.3×3.3-8L		
SYMBOL	MIN	TYP	MAX
A	3.070	3.100	3.130
A1	3.300	3.400	3. 500
b	3.070	3.100	3.130
С	0.770	0.800	0.830
c1		13°	
d	0.275	0.300	0. 325
d1	0.625	0.650	0.675
E	0.144	0.152	0. 160
F	0.300	0. 325	0.350
F1	0.960	0.985	1.010
F2	1.775	1.800	1.825
F3	2.425	2.450	2.475
F4	0.660	0.685	0.710

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## **Contact information**

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